

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>ROGER A. BOOTH JR.</td> <td>12/09/2013</td> </tr> <tr> <td>KANGGUO CHENG</td> <td>10/29/2013</td> </tr> <tr> <td>JOSEPH ERVIN</td> <td>10/30/2013</td> </tr> <tr> <td>CHENGWEN PEI</td> <td>11/29/2013</td> </tr> <tr> <td>RAVI M. TODI</td> <td>11/12/2013</td> </tr> <tr> <td>GENG WANG</td> <td>10/29/2013</td> </tr> </tbody> </table>		Name	Execution Date	ROGER A. BOOTH JR.	12/09/2013	KANGGUO CHENG	10/29/2013	JOSEPH ERVIN	10/30/2013	CHENGWEN PEI	11/29/2013	RAVI M. TODI	11/12/2013	GENG WANG	10/29/2013
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RECEIVING PARTY DATA															
Name:	INTERNATIONAL BUSINESS MACHINES CORPORATION														
Street Address:	NEW ORCHARD ROAD														
City:	ARMONK														
State/Country:	NEW YORK														
Postal Code:	10504														
PROPERTY NUMBERS Total: 1															
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14146198</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14146198										
Property Type	Number														
Application Number:	14146198														
CORRESPONDENCE DATA															
Fax Number:	(516)742-4366														
Phone:	516-742-4343														
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<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>															
Correspondent Name:	SCULLY, SCOTT, MURPHY & PRESSER, P.C.														
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Address Line 2:	SUITE 300														
Address Line 4:	GARDEN CITY, NEW YORK 11530														
NAME OF SUBMITTER:	LESLIE S. SZIVOS														

Signature:	/Leslie S. Szivos/
Date:	01/02/2014
	This document serves as an Oath/Declaration (37 CFR 1.63).
Total Attachments: 15 source=FIS920110186US2_AssignmentDeclaration#page1.tif source=FIS920110186US2_AssignmentDeclaration#page2.tif source=FIS920110186US2_AssignmentDeclaration#page3.tif source=FIS920110186US2_AssignmentDeclaration#page4.tif source=FIS920110186US2_AssignmentDeclaration#page5.tif source=FIS920110186US2_AssignmentDeclaration#page6.tif source=FIS920110186US2_AssignmentDeclaration#page7.tif source=FIS920110186US2_AssignmentDeclaration#page8.tif source=FIS920110186US2_AssignmentDeclaration#page9.tif source=FIS920110186US2_AssignmentDeclaration#page10.tif source=FIS920110186US2_AssignmentDeclaration#page11.tif source=FIS920110186US2_AssignmentDeclaration#page12.tif source=FIS920110186US2_AssignmentDeclaration#page13.tif source=FIS920110186US2_AssignmentDeclaration#page14.tif source=FIS920110186US2_AssignmentDeclaration#page15.tif	

DECLARATION (37 C.F.R. 1.63) FOR UTILITY PATENT APPLICATION USING AN APPLICATION DATA SHEET (37 C.F.R. 1.76) AND ASSIGNMENT

Title of Invention: **DEEP ISOLATION TRENCH STRUCTURE AND DEEP TRENCH CAPACITOR ON A SEMICONDUCTOR-ON-INSULATOR SUBSTRATE**

As a below named inventor, I hereby declare that:

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Whereas, International Business Machines Corporation, a corporation of New York having a place of business at Armonk, New York (herein referred to as "IBM"), desires to acquire, and each undersigned inventor desires to grant to IBM, the entire worldwide right, title, and interest in and to the Invention and in and to any and all patent applications and patents directed thereto;

Now, therefore, for good and valuable consideration, the receipt and sufficiency thereof being hereby acknowledged, each undersigned inventor ("ASSIGNOR") hereby sells or has sold, assigns or has assigned, and otherwise transfers or has transferred to IBM (the "ASSIGNEE"), its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefor in the United States and in all foreign countries and jurisdictions, including all divisions, continuations, reissues, reexaminations, renewals, extensions, counterparts, substitutes, and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, each undersigned inventor hereby authorizes and requests the Director of the United States Patent and Trademark Office to issue any United States Patent, and foreign patent authorities to issue any foreign patent, granted for the Invention, to IBM, its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the same to be held and enjoyed by IBM, its successors, legal representatives, and assigns to the full end of the terms for which any and all such patents may be granted, as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made; and each undersigned inventor agrees to execute any and all documents and instruments and perform all lawful acts reasonably related to recording this Assignment or perfecting title to the Invention and all related patents and applications, in IBM, its successors, legal representatives, and assigns, whenever requested by IBM, its successors, legal representatives, or assigns.

Each undersigned inventor acknowledges their prior and ongoing obligations to sell, assign, and transfer the rights under this Assignment to IBM and is unaware of any reason why they may not have the full and unencumbered right to sell, assign, and transfer the rights hereby sold, assigned, and transferred, and has not executed, and will not execute, any document or instrument in conflict herewith. Each undersigned inventor also hereby grants IBM, its successors, legal representatives, and assigns, the right to insert in this Assignment any further identification (including, but not limited to, patent Application Number) which may be necessary or desirable for recordation of this Assignment. This Assignment is governed by the substantive laws of the State of New York, and any disputes will be resolved in a New York state court or federal court sited in New York.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

(1) Legal Name of Inventor: **Roger A. Booth Jr.**

Signature:  Date: 9-Dec-2013

(2) Legal Name of Inventor: **Kanguo Cheng**

Signature: _____ Date: _____

(3) Legal Name of Inventor: **Joseph Ervin**

Signature: _____ Date: _____

(4) Legal Name of Inventor: **Chengwen Pei**

Signature: _____ Date: _____

(5) Legal Name of Inventor: **Ravi M. Todi**

Signature: _____ Date: _____

(6) Legal Name of Inventor: **Geng Wang**

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(1) Legal Name of Inventor: **Roger A. Booth Jr.**

Signature: _____ Date: _____

(2) Legal Name of Inventor: **Kanguo Cheng**

Signature:  _____ Date: 10/29/2013

(3) Legal Name of Inventor: **Joseph Ervin**

Signature: _____ Date: _____

(4) Legal Name of Inventor: **Chengwen Pei**

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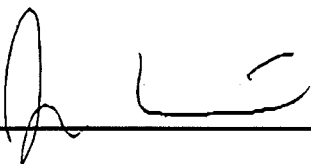
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Signature: _____ Date: _____

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Signature: _____ Date: _____

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Signature:  _____ Date: 16/30/2013

(4) Legal Name of Inventor: **Chengwen Pei**

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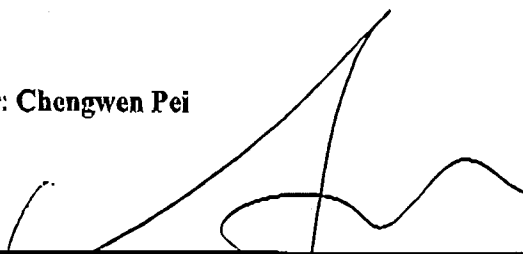
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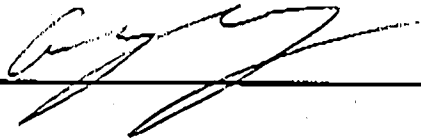
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Signature:  _____ Date: 11/29/2013

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